FAIRCHILD SEMICONDUCTOR®

January 2007

FDMC2610
N-Channel UltraFET Trench® MOSFET
200V, 9.5A, 200mΩ

Features

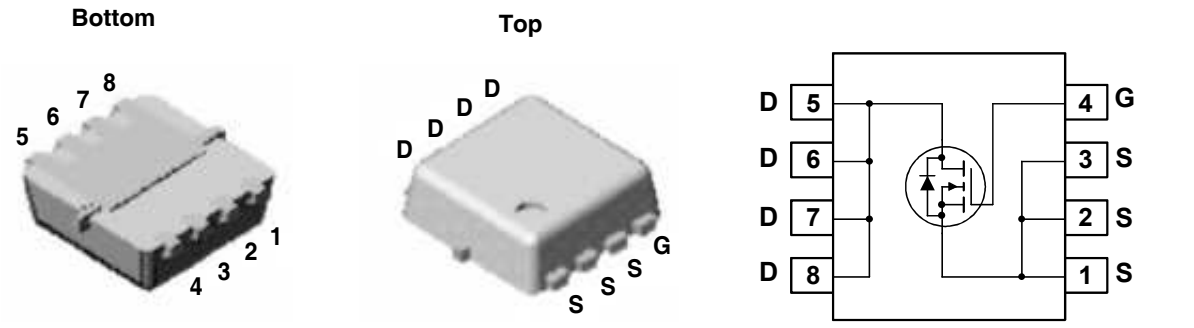
- Max $r_{DS(on)}$ = 200mΩ at V_{GS} = 10V, I_D = 2.2A
- Max $r_{DS(on)}$ = 215mΩ at V_{GS} = 6V, I_D = 1.5A
- Low Profile - 1mm max in a Power 33
- RoHS Compliant

General Description

This N-Channel MOSFET is a rugged gate version of Fairchild Semiconductor's advanced Power Trench process. It has been optimized for power management applications.

Application

- DC - DC Conversion



Power 33

MOSFET Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage			200	V
V_{GS}	Gate to Source Voltage			±20	V
I_D	Drain Current -Continuous (Silicon limited)	T_C = 25°C		9.5	A
	-Continuous	T_A = 25°C	(Note 1a)	2.2	
	-Pulsed			15	
P_D	Power Dissipation	T_C = 25°C		42	W
	Power Dissipation	T_A = 25°C	(Note 1a)	2.1	
T_J, T_{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	3	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	60	

Package Marking and Ordering Information

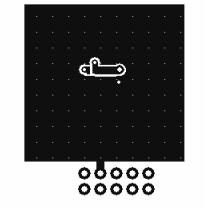
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC2610	FDMC2610	Power 33	7"	8mm	3000 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250μA, V_{GS} = 0V	200			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250μA, referenced to 25°C		199		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 160V, V_{GS} = 0V			1	μA
		V_{DS} = 160V, V_{GS} = 0V, T_J = 125°C			100	
I_{GSS}	Gate to Source Leakage Current	V_{GS} = ±20V, V_{DS} = 0V			±100	nA
On Characteristics						
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250μA	2	3.2	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250μA, referenced to 25°C		-9.9		mV/°C
$r_{DS(on)}$	Drain to Source On Resistance	V_{GS} = 10V, I_D = 2.2A		175	200	mΩ
		V_{GS} = 6V, I_D = 1.5A		188	215	
		V_{GS} = 10V, I_D = 2.2A , T_J = 125°C		347	397	
g_{FS}	Forward Transconductance	V_{DS} = 5V, I_D = 2.2A		7		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 100V, V_{GS} = 0V, f = 1MHz		720	960	pF
C_{oss}	Output Capacitance			41	55	pF
C_{rss}	Reverse Transfer Capacitance			12	20	pF
R_g	Gate Resistance	f = 1MHz		0.7		Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 100V, I_D = 2.2A, V_{GS} = 10V, R_{GEN} = 24Ω		17	31	ns
t_r	Rise Time			13	24	ns
$t_{d(off)}$	Turn-Off Delay Time			29	47	ns
t_f	Fall Time			16	29	ns
$Q_{g(TOT)}$	Total Gate Charge at 10V	V_{GS} = 0V to 10V, V_{DD} = 100V, I_D = 2.2A		12.3	18	nC
Q_{gs}	Gate to Source Gate Charge			3		nC
Q_{gd}	Gate to Drain “Miller” Charge			3.6		nC
Drain-Source Diode Characteristics						
V_{SD}	Source to Drain Diode Forward Voltage	V_{GS} = 0V, I_S = 2.2A (Note 2)		0.8	1.2	V
t_{rr}	Reverse Recovery Time	I_F = 2.2A, di/dt = 100A/μs		69	104	ns
Q_{rr}	Reverse Recovery Charge			114	171	nC

Notes:

1: $R_{\theta JA}$ is determined with the device mounted on a 1in^2 pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 60°C/W when mounted on a 1 in^2 pad of 2 oz copper

b. 135°C/W when mounted on a minimum pad of 2 oz copper

2: Pulse Test: Pulse Width < 300μs, Duty cycle < 2.0%.

Typical Characteristics T_J = 25°C unless otherwise noted

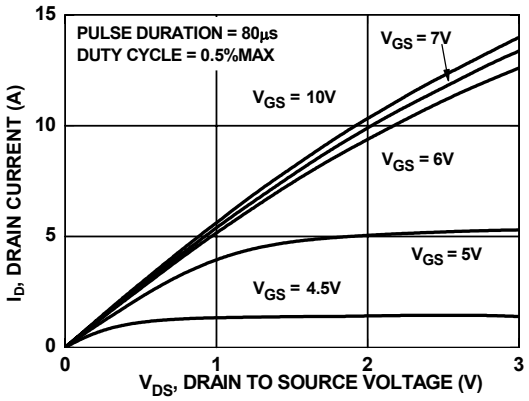


Figure 1. On-Region Characteristics

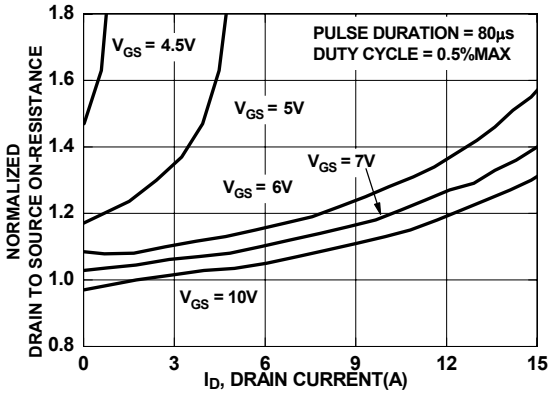


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

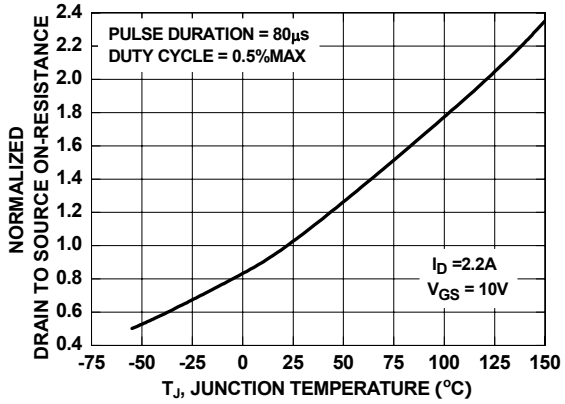


Figure 3. Normalized On-Resistance vs Junction Temperature

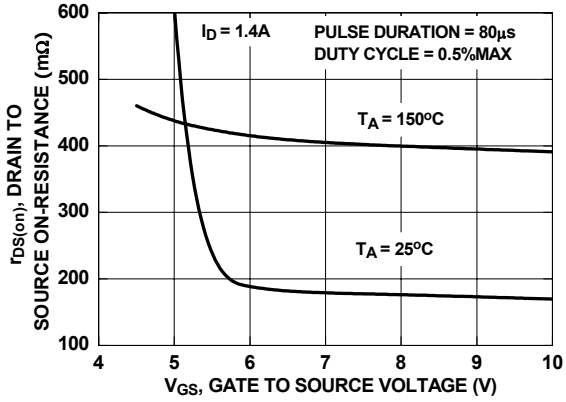


Figure 4. On-Resistance vs Gate to Source Voltage

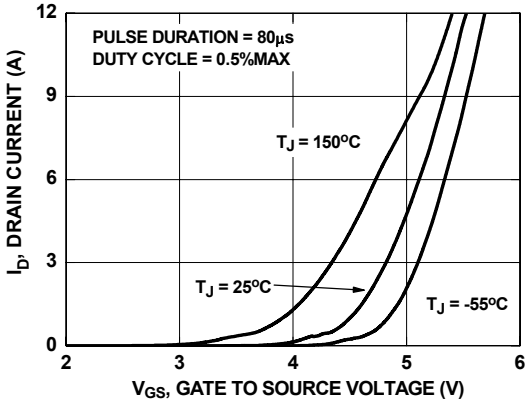


Figure 5. Transfer Characteristics

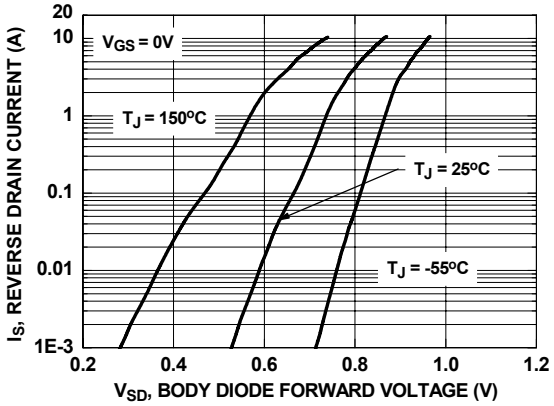


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25°C unless otherwise noted

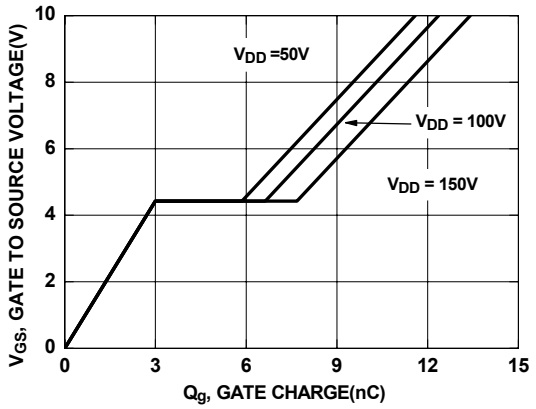


Figure 7. Gate Charge Characteristics

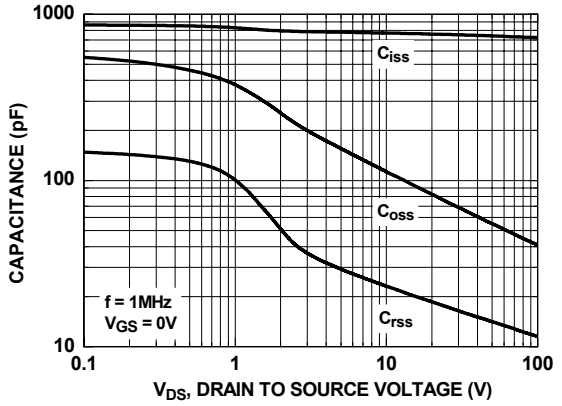


Figure 8. Capacitance vs Drain to Source Voltage

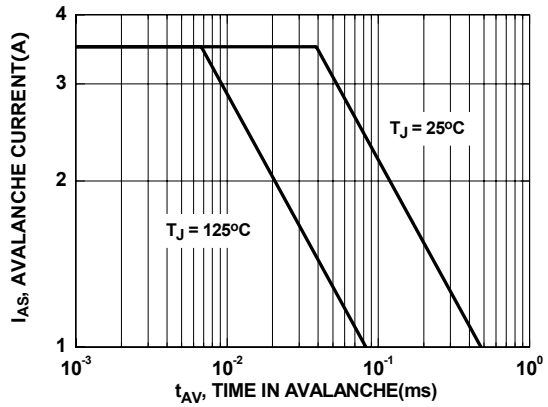


Figure 9. Unclamped Inductive Switching Capability

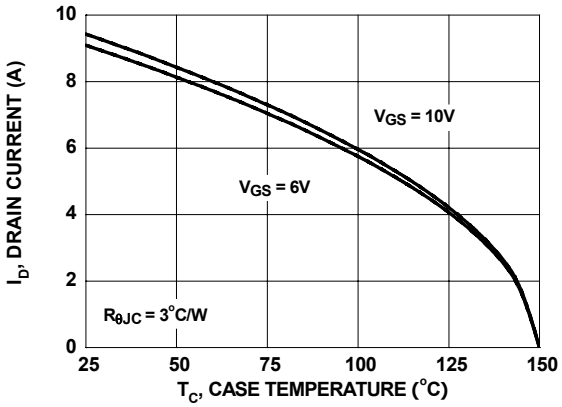


Figure 10. Maximum Continuous Drain Current vs Case Temperature

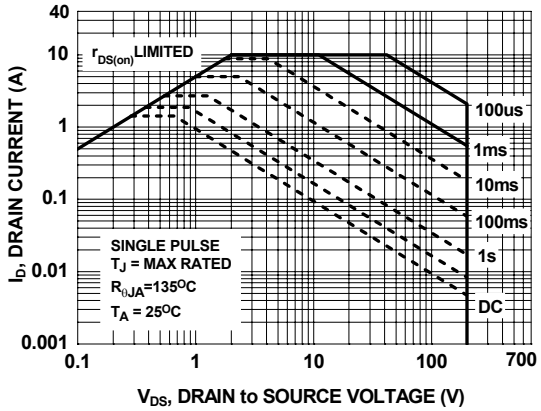


Figure 11. Forward Bias Safe Operating Area

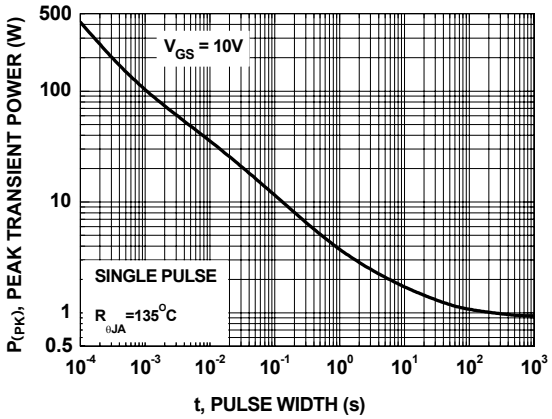


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25°C unless otherwise noted

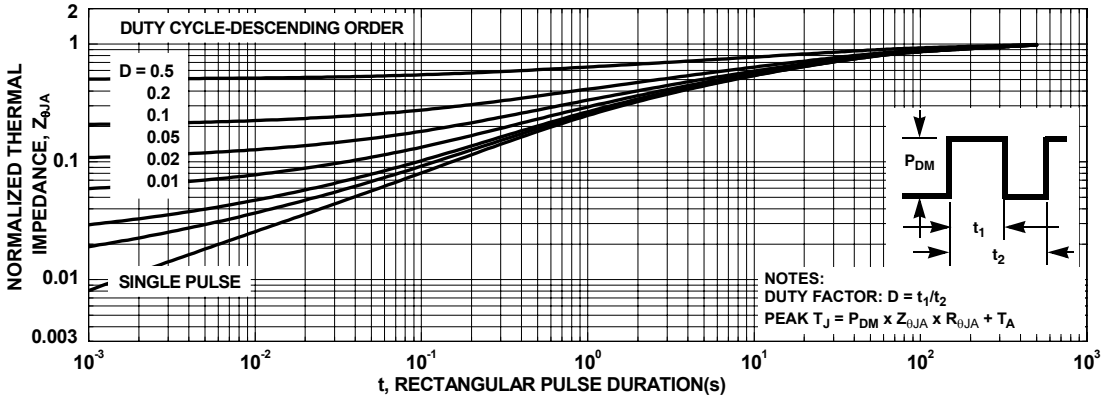
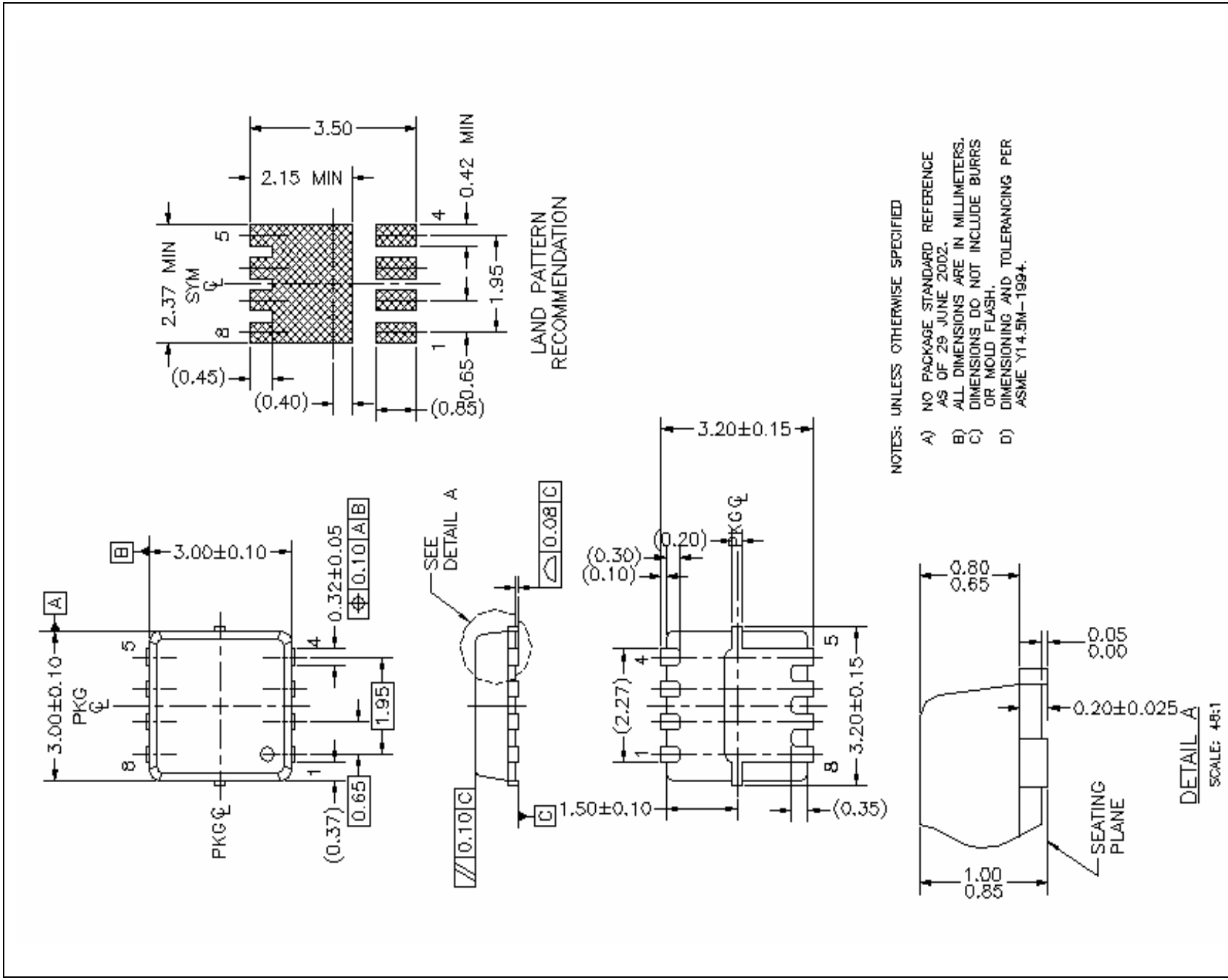


Figure 13. Transient Thermal Response Curve


3.50
2.15 MIN
0.42 MIN
2.37 MIN
SYM
1.95
(0.45)
(0.40)
0.65
(0.85)
LAND PATTERN
RECOMMENDATION
3.00±0.10
0.32±0.05
0.10 A B
PKG
1.95
0.65
(0.37)
SEE
DETAIL A
0.08 C
0.10 C
1.50±0.10
3.20±0.15
(0.20)
(0.30)
(0.10)
(2.27)
3.20±0.15
(0.35)
NOTES: UNLESS OTHERWISE SPECIFIED
A) NO PACKAGE STANDARD REFERENCE AS OF 29 JUNE 2002.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH.
D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
0.80
0.55
0.05
0.00
0.20±0.025
SEATING
PLANE
1.00
0.85
DETAIL A
SCALE: 4:1

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EnSigna™	LittleFET™	PowerTrench®	TCM™	
FACT®	MICROCOUPLER™	QFET®	TinyBoost™	
FAST®	MicroFET™	QS™	TinyBuck™	
FASTr™	MicroPak™	QT Optoelectronics™	TinyPWM™	
FPS™	MICROWIRE™	Quiet Series™	TinyPower™	
FRFET™	MSX™	RapidConfigure™	TinyLogic®	
	MSXPro™	RapidConnect™	TINYOPTO™	
Across the board. Around the world.™		µSerDes™	TruTranslation™	
The Power Franchise®		ScalarPump™	UHC®	
Programmable Active Droop™				

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Definition of Terms

Datasheet Identification	Product Status	Definition
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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